

具有单使能端的

TS3USB221 高速 USB 2.0 (480Mbps) 1:2 多路复用器 – 多路信号分离器

1 特性

- V_{CC} 工作电压为 2.3 V 至 3.6 V
- V_{IO} 支持高达 5.5V 的信号
- 1.8V 兼容控制引脚输入
- \overline{OE} 禁用时采用低功耗模式 (1 μ A)
- $r_{ON} = 6\Omega$ (最大值)
- $\Delta r_{ON} = 0.2\Omega$ (典型值)
- $C_{io(on)} = 6pF$ (最大值)
- 低功耗 (最大值为 30 μ A)
- ESD > 2000V 人体放电模型 (HBM)
- 高带宽: 1.1GHz (典型值)

2 应用

- 为 USB 1.0、1.1 和 2.0 路由信号
- 移动行业处理器接口 (MIPI™) 信号路由
- MHL 1.0

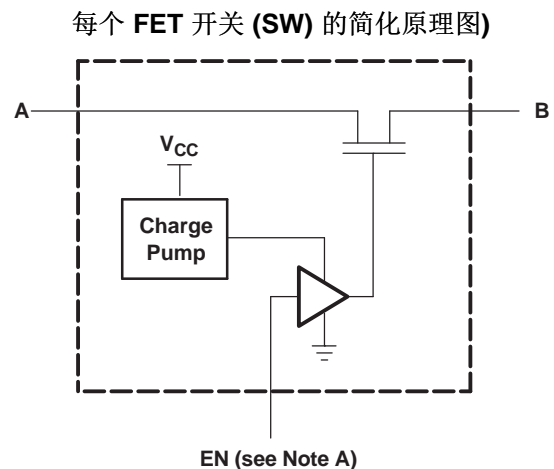
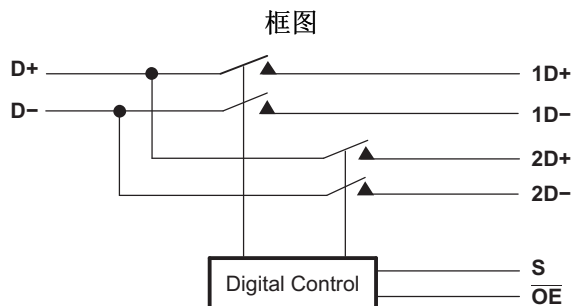
3 说明

TS3USB221 是一款高带宽开关, 专为电话和消费型应用 (例如: 手机、数码相机、带集线器的笔记本电脑或带电流限制的 USB I/O) 中的高速 USB 2.0 信号的转换而设计。此开关具有较宽的带宽 (1.1GHz), 这一特性使得信号传递具有最少的边缘失真和相位失真。该器件将 USB 主机器件差动输出复用到一个相应的输出 (共两个输出)。此开关为双向开关, 输出端高速信号具有极少或零衰减。TS3USB221 能实现低位间偏移和高通道间噪声隔离。TS3USB221 同样能够兼容各种标准, 例如高速 USB 2.0 (480Mbps)。

器件信息⁽¹⁾

器件型号	封装	封装尺寸 (标称值)
TS3USB221	VSON (10)	3.00mm × 3.00mm
	UQFN (10)	1.50mm × 2.00mm

(1) 如需了解所有可用封装, 请参阅数据表末尾的可订购产品附录。



A. EN 是应用于开关的内部启用信号。

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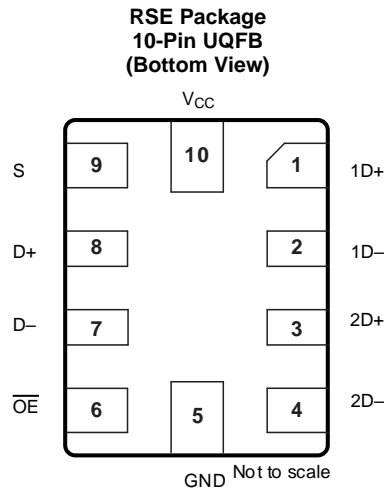
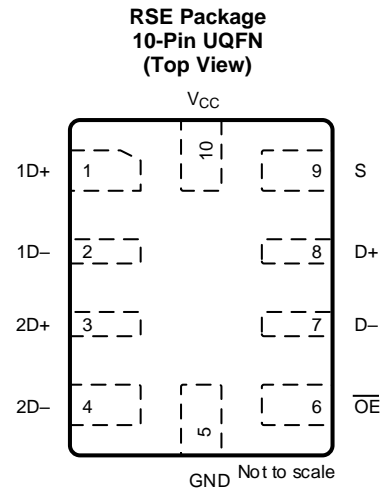
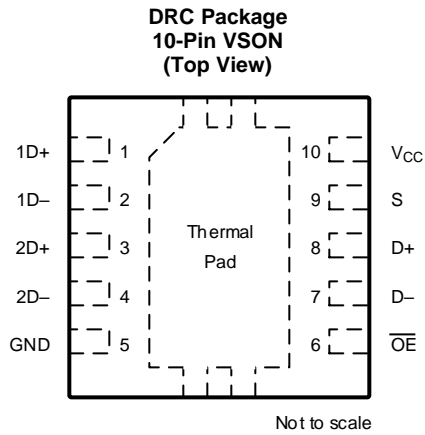
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4 修订历史记录

注：之前版本的页码可能与当前版本有所不同。

Changes from Revision I (January 2016) to Revision J	Page
• Added CDM value and table notes to the <i>ESD Ratings</i>	4
Changes from Revision H (February 2015) to Revision I	Page
• Changed V_{IH} Max from 5.5 to V_{CC} in <i>Recommended Operating Conditions</i> table	4
Changes from Revision G (September 2010) to Revision H	Page
• 已更改 将特性的 第一项 从“ V_{CC} 工作电压为 2.5 V 至 3.3 V”改为“ V_{CC} 工作电压为 2.3 V 和 3.6 V”	1
• 已添加 引脚配置和功能 部分、 <i>ESD</i> 额定值 表、特性 说明 部分、器件功能模式、应用和实施 部分、电源相关建议 部分、布局 部分、器件和文档支持 部分以及机械、封装和可订购信息 部分	1
• 删除了 订购信息 表	1

5 Pin Configuration and Functions



Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
1D+	1	I/O	USB port 1
1D-	2	I/O	
2D+	3	I/O	USB port 2
2D-	4	I/O	
GND	5	—	Ground
$\overline{\text{OE}}$	6	I	Bus-switch enable
D-	7	I/O	Common USB port
D+	8	I/O	
S	9	I	Select input
V _{CC}	10	—	Supply voltage

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			MIN	MAX	UNIT
V _{CC}	Supply voltage		−0.5	4.6	V
V _{IN}	Control input voltage ^{(2) (3)}		−0.5	7	V
V _{I/O}	Switch I/O voltage ^{(2) (3) (4)}		−0.5	7	V
I _{IK}	Control input clamp current	V _{IN} < 0		−50	mA
I _{I/OK}	I/O port clamp current	V _{I/O} < 0		−50	mA
I _{I/O}	ON-state switch current ⁽⁵⁾			±120	mA
	Continuous current through V _{CC} or GND			±100	mA
T _{stg}	Storage temperature		−65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltages are with respect to ground, unless otherwise specified.

(3) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

(4) V_I and V_O are used to denote specific conditions for V_{I/O}.

(5) I_I and I_O are used to denote specific conditions for I_{I/O}.

6.2 ESD Ratings

		VALUE	UNIT	
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±1500	V

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

See ⁽¹⁾.

			MIN	MAX	UNIT
V _{CC}	Supply voltage		2.3	3.6	V
V _{IH}	High-level control input voltage	V _{CC} = 2.3 V to 2.7 V	0.46 × V _{CC}	V _{CC}	V
		V _{CC} = 2.7 V to 3.6 V			
V _{IL}	Low-level control input voltage	V _{CC} = 2.3 V to 2.7 V	0	0.25 × V _{CC}	V
		V _{CC} = 2.7 V to 3.6 V			
V _{I/O}	Data input/output voltage		0	5.5	V
T _A	Operating free-air temperature		−40	85	°C

(1) All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		TS3USB221		UNIT
		DRC (VSON)	RSE (UQFN)	
		10 PINS	10 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	57.7	169.8	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	87.7	84.7	
R _{θJB}	Junction-to-board thermal resistance	32.6	94.9	
ψ _{JT}	Junction-to-top characterization parameter	8.2	5.7	
ψ _{JB}	Junction-to-board characterization parameter	32.8	94.9	
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	18.5	N/A	

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

6.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

PARAMETER	TEST CONDITIONS		MIN	TYP ⁽²⁾	MAX	UNIT
V_{IK}	$V_{CC} = 3.6\text{ V}, 2.7\text{ V},$	$I_I = -18\text{ mA}$			-1.8	V
I_{IN} Control inputs	$V_{CC} = 3.6\text{ V}, 2.7\text{ V}, 0\text{ V},$	$V_{IN} = 0\text{ V to } 3.6\text{ V}$			± 1	μA
I_{OZ} ⁽³⁾	$V_{CC} = 3.6\text{ V}, 2.7\text{ V},$ $V_O = 0\text{ V to } 3.6\text{ V}, V_I = 0\text{ V},$	$V_{IN} = V_{CC}$ or GND, Switch OFF			± 1	μA
I_{OFF}	$V_{CC} = 0\text{ V}$	$V_{I/O} = 0\text{ V to } 3.6\text{ V}$			± 2	μA
		$V_{I/O} = 0\text{ V to } 2.7\text{ V}$			± 1	
I_{CC}	$V_{CC} = 3.6\text{ V}, 2.7\text{ V},$ $V_{IN} = V_{CC}$ or GND,	$I_{I/O} = 0\text{ V},$ Switch ON or OFF			30	μA
I_{CC} (low power mode)	$V_{CC} = 3.6\text{ V}, 2.7\text{ V},$ $V_{IN} = V_{CC}$ or GND	Switch disabled (OE in high state)			1	μA
ΔI_{CC} ⁽⁴⁾ Control inputs	One input at 1.8 V, Other inputs at V_{CC} or GND	$V_{CC} = 3.6\text{ V}$			20	μA
		$V_{CC} = 2.7\text{ V}$			0.5	
C_{in} Control inputs	$V_{CC} = 3.3\text{ V}, 2.5\text{ V},$	$V_{IN} = 3.3\text{ V or } 0\text{ V}$		1	2	pF
$C_{io(OFF)}$	$V_{CC} = 3.3\text{ V}, 2.5\text{ V},$	$V_{I/O} = 3.3\text{ V or } 0\text{ V},$ Switch OFF		3	4	pF
$C_{io(ON)}$	$V_{CC} = 3.3\text{ V}, 2.5\text{ V},$	$V_{I/O} = 3.3\text{ V or } 0\text{ V},$ Switch ON		5	6	pF
r_{on} ⁽⁵⁾	$V_{CC} = 3\text{ V}, 2.3\text{ V}$	$V_I = 0\text{ V},$ $I_O = 30\text{ mA}$			6	Ω
		$V_I = 2.4\text{ V},$ $I_O = -15\text{ mA}$			6	
Δr_{on}	$V_{CC} = 3\text{ V}, 2.3\text{ V}$	$V_I = 0\text{ V},$ $I_O = 30\text{ mA}$		0.2		Ω
		$V_I = 1.7,$ $I_O = -15\text{ mA}$		0.2		
$r_{on(Flat)}$	$V_{CC} = 3\text{ V}, 2.3\text{ V}$	$V_I = 0\text{ V},$ $I_O = 30\text{ mA}$		1		Ω
		$V_I = 1.7,$ $I_O = -15\text{ mA}$		1		

(1) V_{IN} and I_{IN} refer to control inputs. V_I , V_O , I_I , and I_O refer to data pins.

(2) All typical values are at $V_{CC} = 3.3\text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

(3) For I/O ports, the parameter I_{OZ} includes the input leakage current.

(4) This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

(5) Measured by the voltage drop between the A and B terminals at the indicated current through the switch. ON-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

6.6 Dynamic Electrical Characteristics, $V_{CC} = 3.3\text{ V} \pm 10\%$

 over operating range, $T_A = -40^\circ\text{C}$ to 85°C , $V_{CC} = 3.3\text{ V} \pm 10\%$, $GND = 0\text{ V}$

PARAMETER		TEST CONDITIONS	TYP ⁽¹⁾	UNIT
X_{TALK}	Crosstalk	$R_L = 50\ \Omega$, $f = 250\text{ MHz}$	-40	dB
O_{IRR}	OFF isolation	$R_L = 50\ \Omega$, $f = 250\text{ MHz}$	-41	dB
BW	Bandwidth (-3 dB)	$R_L = 50\ \Omega$	1.1	GHz

 (1) For Maximum or Minimum conditions, use the appropriate value specified under [Electrical Characteristics](#) for the applicable device type.

6.7 Dynamic Electrical Characteristics, $V_{CC} = 2.5\text{ V} \pm 10\%$

 over operating range, $T_A = -40^\circ\text{C}$ to 85°C , $V_{CC} = 2.5\text{ V} \pm 10\%$, $GND = 0\text{ V}$

PARAMETER		TEST CONDITIONS	TYP ⁽¹⁾	UNIT
X_{TALK}	Crosstalk	$R_L = 50\ \Omega$, $f = 250\text{ MHz}$	-39	dB
O_{IRR}	OFF isolation	$R_L = 50\ \Omega$, $f = 250\text{ MHz}$	-40	dB
BW	Bandwidth (-3 dB)	$R_L = 50\ \Omega$	1.1	GHz

 (1) For Maximum or Minimum conditions, use the appropriate value specified under [Electrical Characteristics](#) for the applicable device type.

6.8 Switching Characteristics, $V_{CC} = 3.3\text{ V} \pm 10\%$

 over operating range, $T_A = -40^\circ\text{C}$ to 85°C , $V_{CC} = 3.3\text{ V} \pm 10\%$, $GND = 0\text{ V}$

PARAMETER		MIN	TYP ⁽¹⁾	MAX	UNIT
t_{pd}	Propagation delay ^{(2) (3)}		0.25		ns
t_{ON}	Line enable time	S to D, nD		30	ns
		\overline{OE} to D, nD		17	
t_{OFF}	Line disable time	S to D, nD		12	ns
		\overline{OE} to D, nD		10	
$t_{SK(O)}$	Output skew between center port to any other port ⁽²⁾		0.1	0.2	ns
$t_{SK(P)}$	Skew between opposite transitions of the same output ($t_{PHL} - t_{PLH}$) ⁽²⁾		0.1	0.2	ns

 (1) For Maximum or Minimum conditions, use the appropriate value specified under [Electrical Characteristics](#) for the applicable device type.

(2) Specified by design

(3) The bus switch contributes no propagational delay other than the RC delay of the on resistance of the switch and the load capacitance. The time constant for the switch alone is of the order of 0.25 ns for 10-pF load. This time constant adds very little propagational delay to the system because it is much smaller than the rise/fall times of typical driving signals. Propagational delay of the bus switch, when used in a system, is determined by the driving circuit on the driving side of the switch and its interactions with the load on the driven side.

6.9 Switching Characteristics, $V_{CC} = 2.5\text{ V} \pm 10\%$

 over operating range, $T_A = -40^\circ\text{C}$ to 85°C , $V_{CC} = 2.5\text{ V} \pm 10\%$, $GND = 0\text{ V}$

PARAMETER		MIN	TYP ⁽¹⁾	MAX	UNIT
t_{pd}	Propagation delay ^{(2) (3)}		0.25		ns
t_{ON}	Line enable time	S to D, nD		50	ns
		\overline{OE} to D, nD		32	
t_{OFF}	Line disable time	S to D, nD		23	ns
		\overline{OE} to D, nD		12	
$t_{SK(O)}$	Output skew between center port to any other port ⁽²⁾		0.1	0.2	ns
$t_{SK(P)}$	Skew between opposite transitions of the same output ($t_{PHL} - t_{PLH}$) ⁽²⁾		0.1	0.2	ns

 (1) For Maximum or Minimum conditions, use the appropriate value specified under [Electrical Characteristics](#) for the applicable device type.

(2) Specified by design

(3) The bus switch contributes no propagational delay other than the RC delay of the on resistance of the switch and the load capacitance. The time constant for the switch alone is of the order of 0.25 ns for 10-pF load. The time constraint adds very little propagational delay to the system because it is much smaller than the rise and fall times of typical driving signals. Propagational delay of the bus switch, when used in a system, is determined by the driving circuit on the driving side of the switch and its interactions with the load on the driven side.

6.10 Typical Characteristics

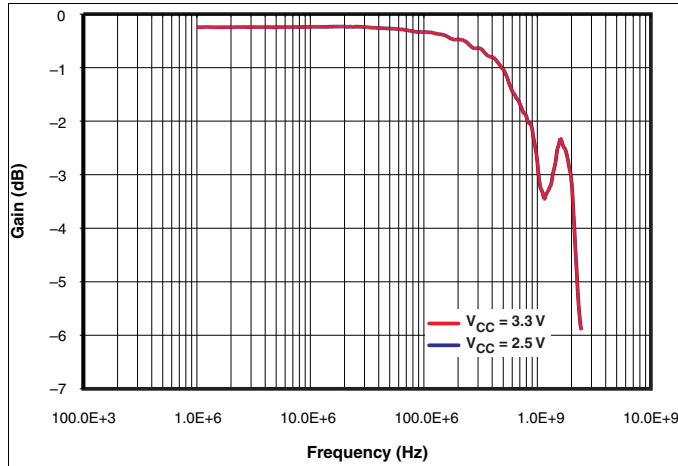


Figure 1. Gain vs Frequency

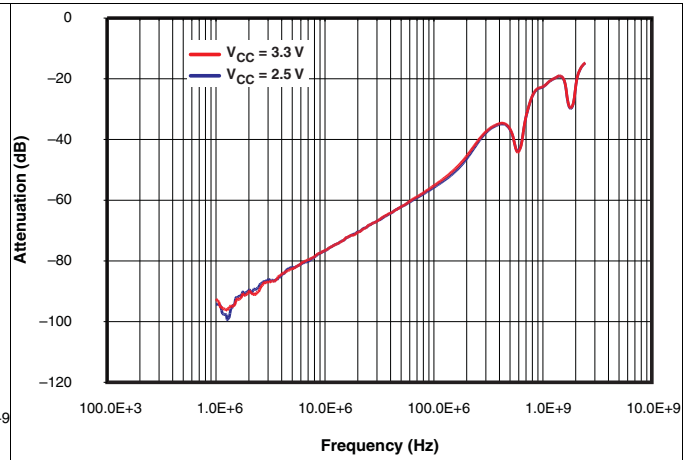


Figure 2. OFF Isolation vs Frequency

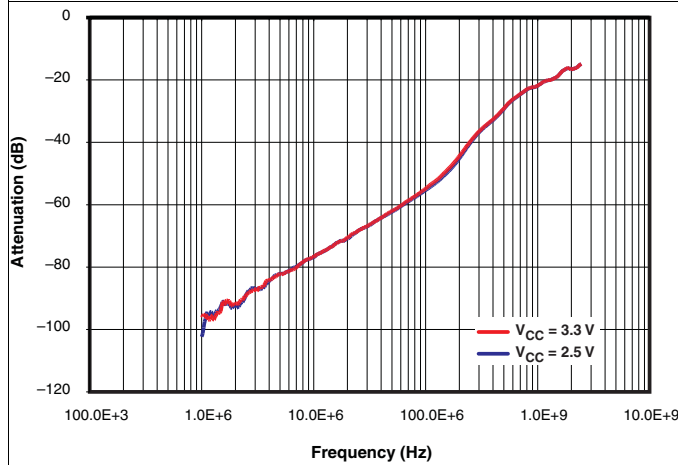


Figure 3. Crosstalk vs Frequency

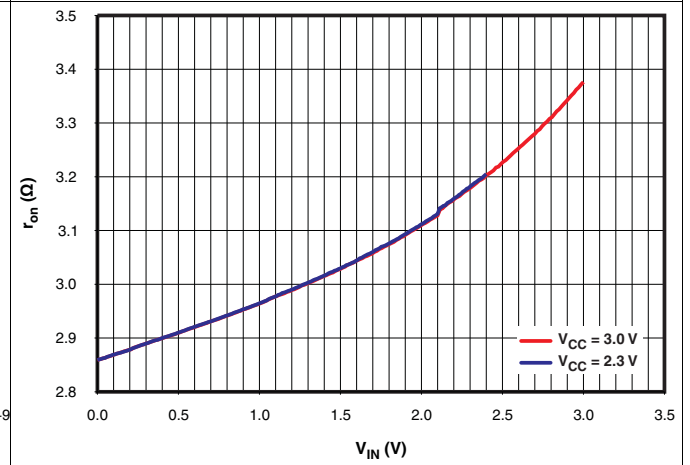


Figure 4. r_{on} vs V_{IN} ($I_{OUT} = -15$ mA)

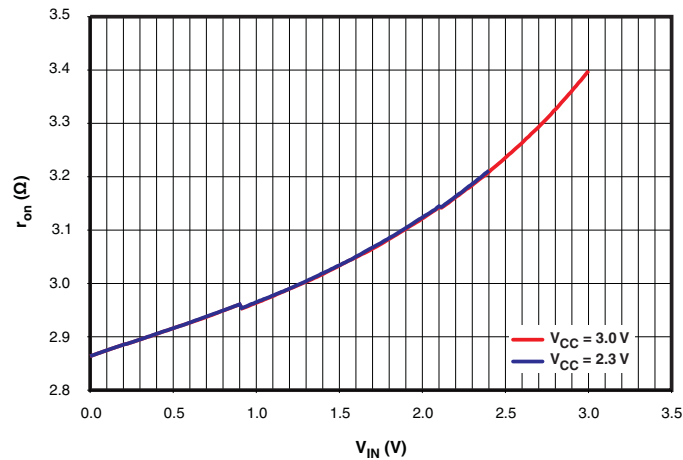
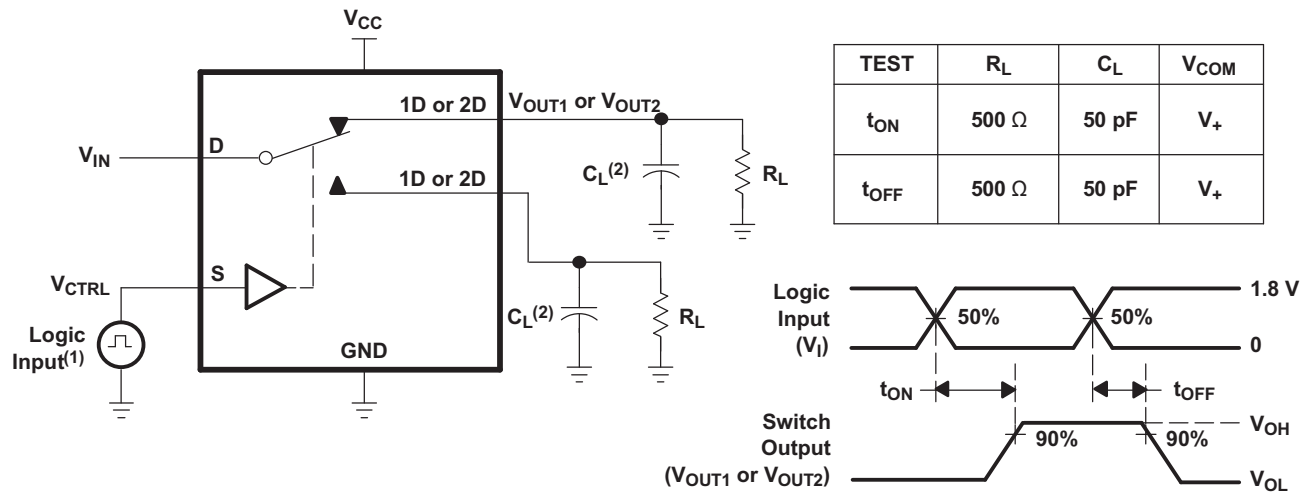


Figure 5. r_{on} vs V_{IN} ($I_{OUT} = -30$ mA)

7 Parameter Measurement Information



(1) All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $t_r < 5$ ns, $t_f < 5$ ns.

(2) C_L includes probe and jig capacitance.

Figure 6. Turnon (t_{ON}) and Turnoff Time (t_{OFF})

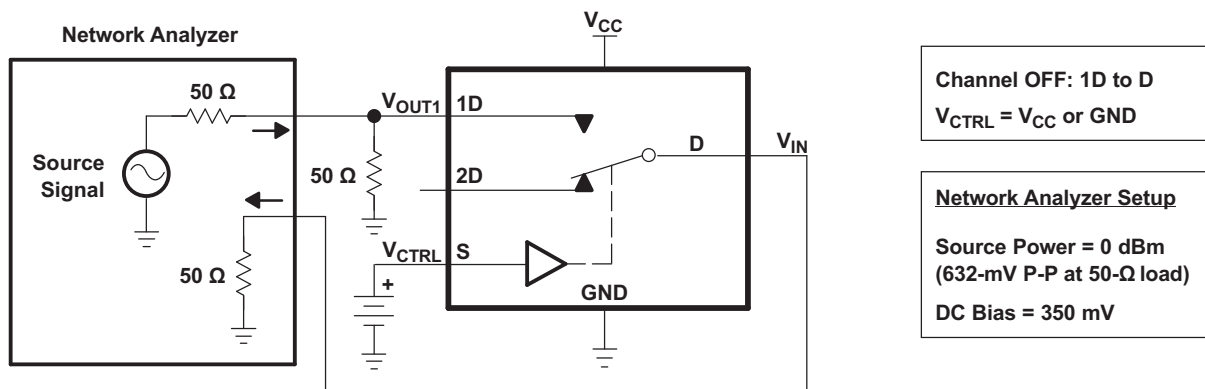


Figure 7. OFF Isolation (O_{ISO})

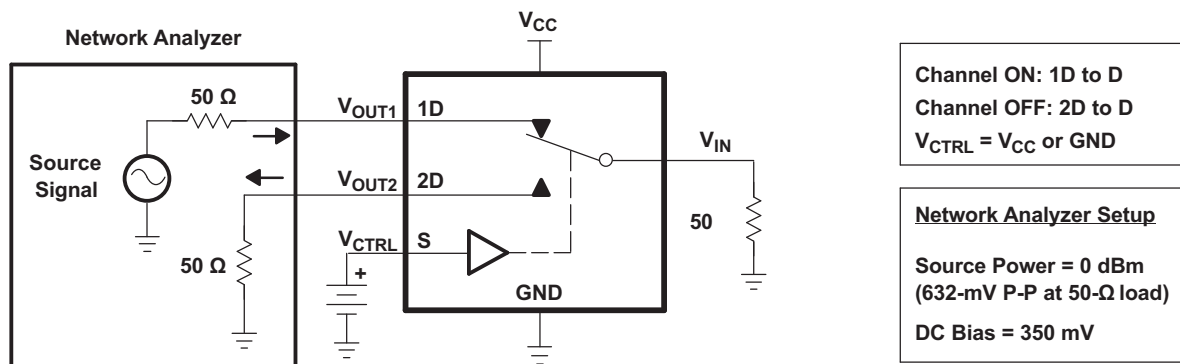


Figure 8. Crosstalk (X_{TALK})

Parameter Measurement Information (continued)

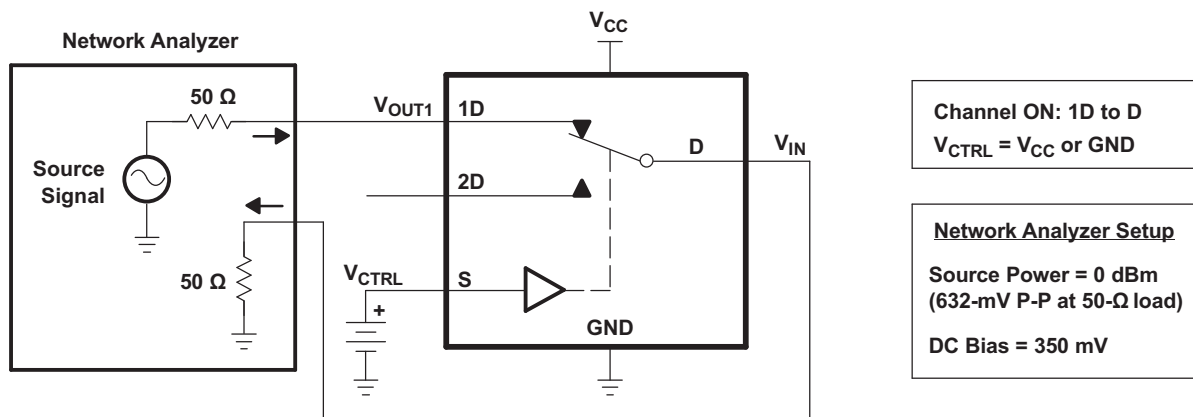


Figure 9. Bandwidth (BW)

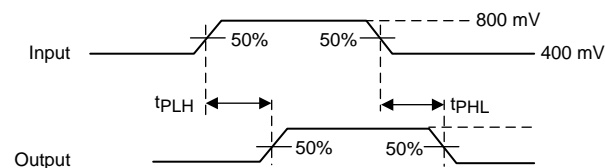
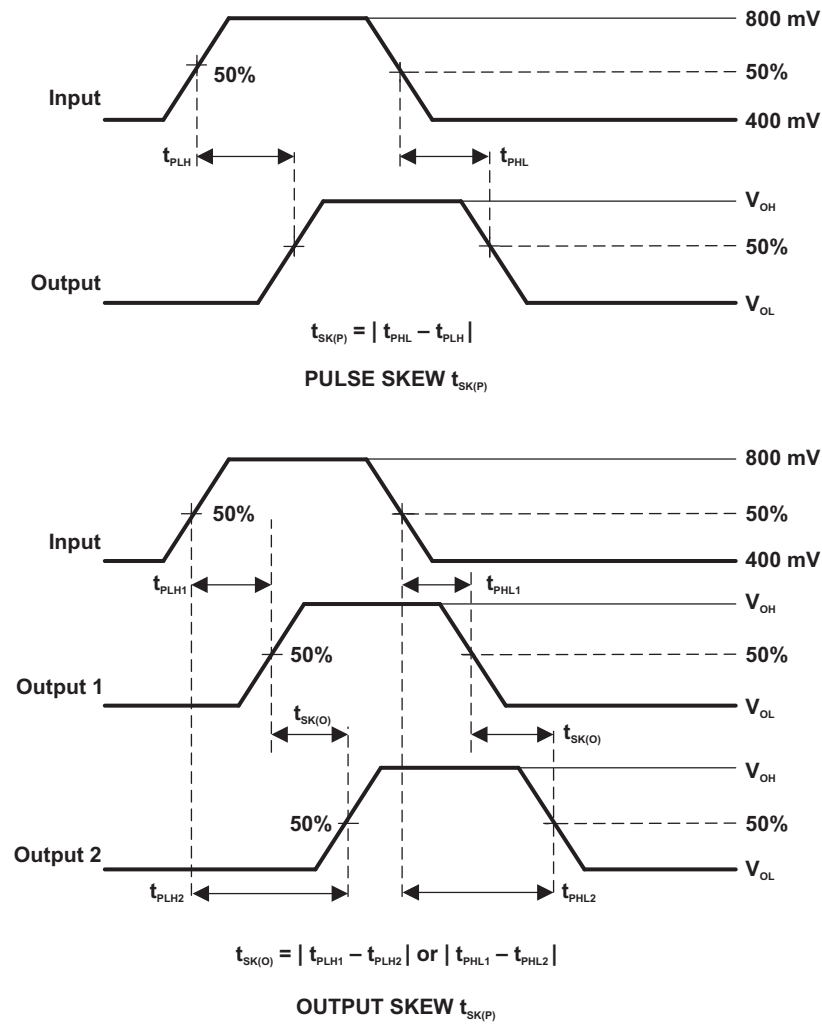
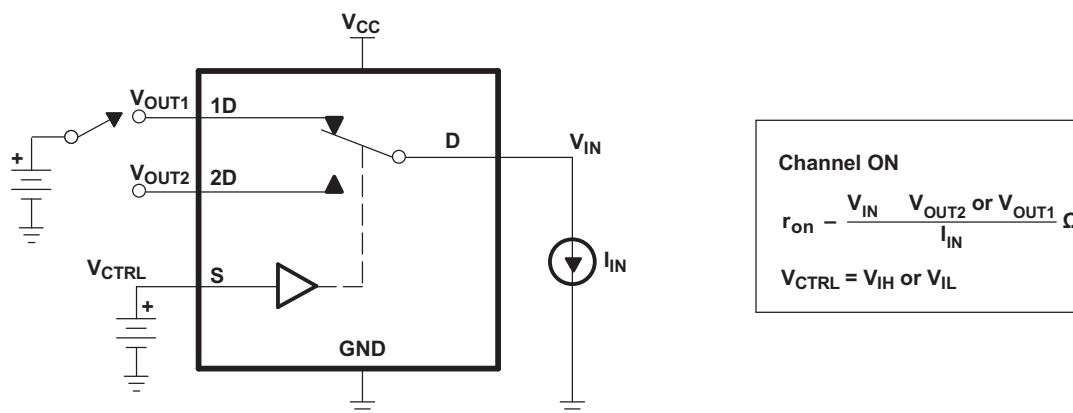


Figure 10. Propagation Delay

Parameter Measurement Information (continued)

Figure 11. Skew Test

Figure 12. ON-State Resistance (r_{on})

Parameter Measurement Information (continued)

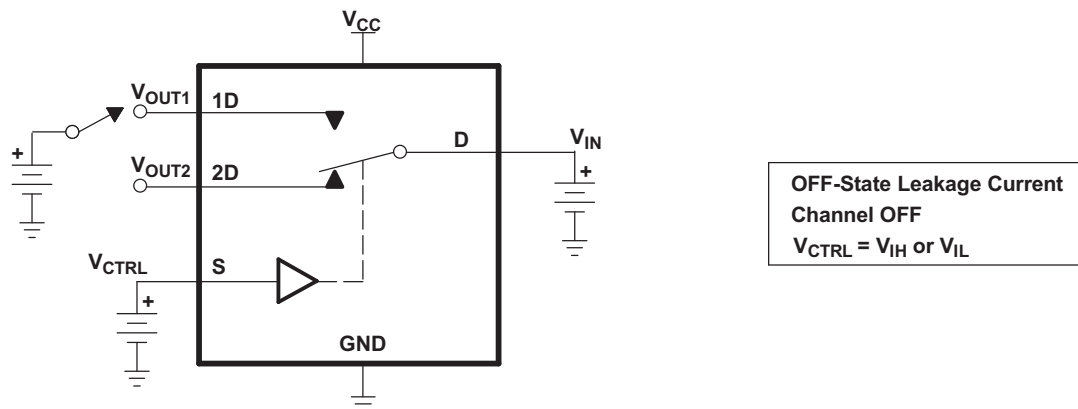


Figure 13. OFF-State Leakage Current

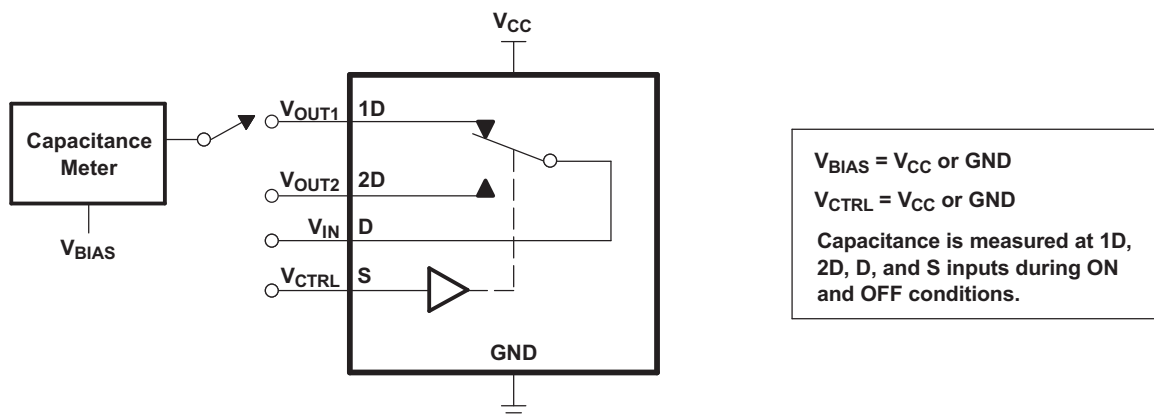


Figure 14. Capacitance

8 Detailed Description

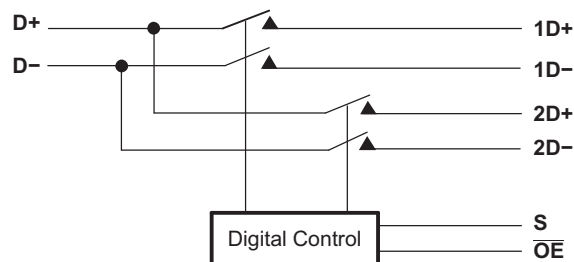
8.1 Overview

The TS3USB221 device is a 2-channel SPDT switch specially designed for the switching of high-speed USB 2.0 signals in handset and consumer applications, such as cell phones, digital cameras, and notebooks with hubs or controllers with limited USB I/Os. The wide bandwidth (1.1 GHz) of this switch allows signals to pass with minimum edge and phase distortion. The device multiplexes differential outputs from a USB host device to one of two corresponding outputs. The switch is bidirectional and offers little or no attenuation of the high-speed signals at the outputs. The device also has a low power mode that reduces the power consumption to 1 μ A for portable applications with a battery or limited power budget.

The device is designed for low bit-to-bit skew and high channel-to-channel noise isolation, and is compatible with various standards, such as high-speed USB 2.0 (480 Mbps).

The TS3USB221 device integrates ESD protection cells on all pins, is available in a tiny μ QFN package (2 mm \times 1.5 mm) and is characterized over the free-air temperature range from -40°C to 85°C .

8.2 Functional Block Diagram



8.3 Feature Description

8.3.1 Low Power Mode

The TS3USB221 has a low power mode that reduces the power consumption to 1 μ A when the device is not in use. The bus-switch enable pin $\overline{\text{OE}}$ must be supplied with a logic high signal to put the device in low power mode and disable the switch.

8.4 Device Functional Modes

Table 1. Truth Table

S	$\overline{\text{OE}}$	FUNCTION
X	H	Disconnect
L	L	D = 1D
H	L	D = 2D

9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

There are many USB applications in which the USB hubs or controllers have a limited number of USB I/Os. The TS3USB221 solution can effectively expand the limited USB I/Os by switching between multiple USB buses in order to interface them to a single USB hub or controller. TS3USB221 can also be used to connect a single controller to two USB connectors.

9.2 Typical Application

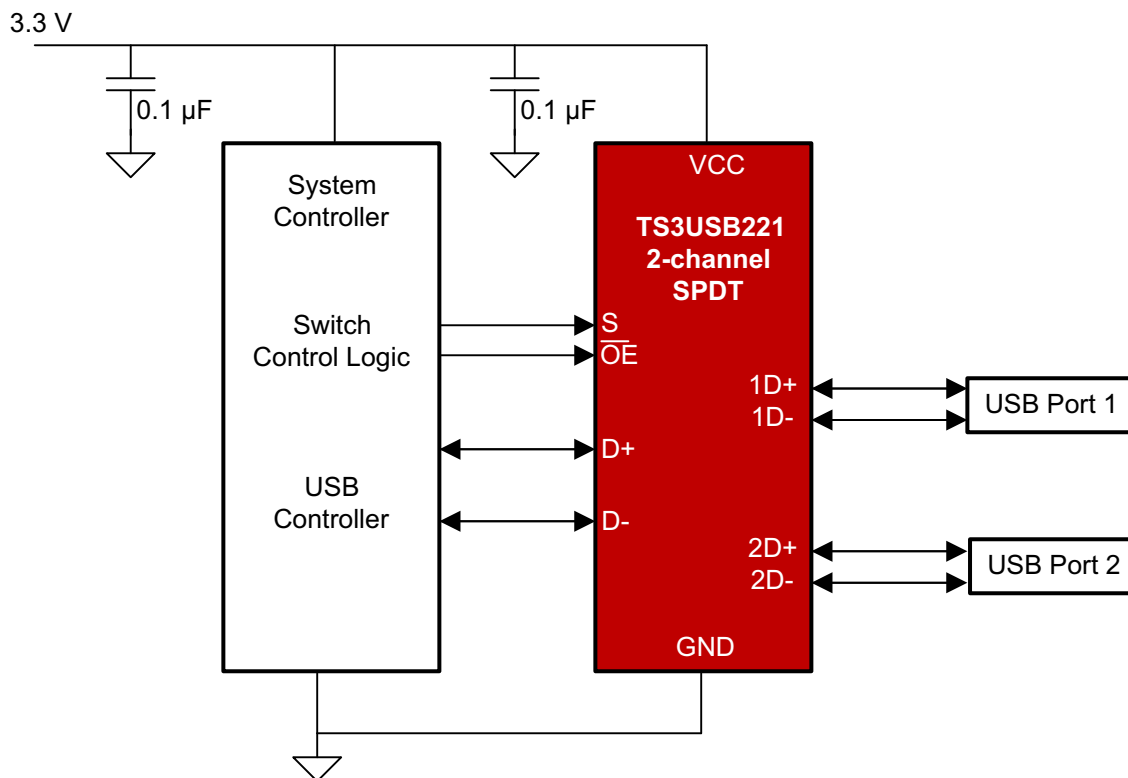


Figure 15. Simplified Schematic

9.2.1 Design Requirements

Design requirements of the USB 1.0, 1.1, and 2.0 standards should be followed.

TI recommends that the digital control pins S and \overline{OE} be pulled up to V_{CC} or down to GND to avoid undesired switch positions that could result from the floating pin.

9.2.2 Detailed Design Procedure

The TS3USB221 may be properly operated without any external components. However, it is recommended that unused pins be connected to ground through a 50-Ω resistor to prevent signal reflections back into the device.

Typical Application (continued)

9.2.3 Application Curves

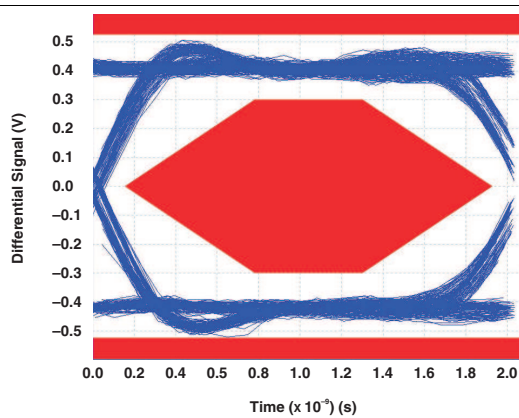


Figure 16. Eye Pattern: 480-Mbps USB Signal With No Switch (Through Path)

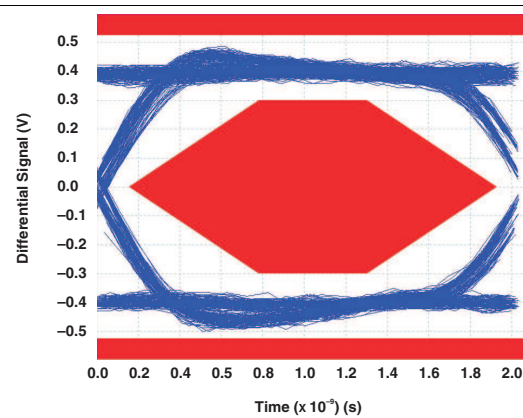


Figure 17. Eye Pattern: 480-Mbps USB Signal With Switch NC Path

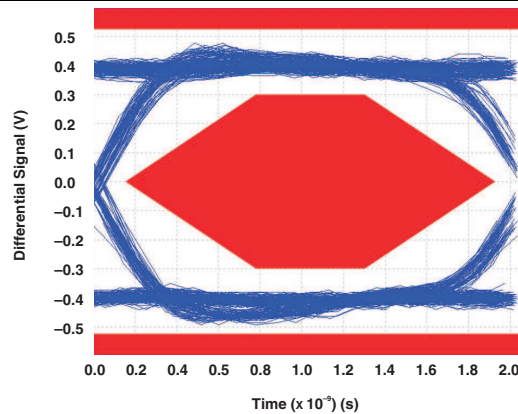


Figure 18. Eye Pattern: 480-Mbps USB Signal With Switch NO Path

10 Power Supply Recommendations

Power to the device is supplied through the V_{CC} pin and should follow the USB 1.0, 1.1, and 2.0 standards. TI recommends placing a bypass capacitor as close as possible to the supply pin V_{CC} to help smooth out lower frequency noise to provide better load regulation across the frequency spectrum.

11 Layout

11.1 Layout Guidelines

Place supply bypass capacitors as close to V_{CC} pin as possible. Avoid placing the bypass caps near the D+/D– traces.

The high-speed D+/D– traces should always be matched lengths and must be no more than 4 inches, otherwise the eye diagram performance may be degraded. A high-speed USB connection is made through a shielded, twisted pair cable with a differential characteristic impedance. In the layout, the impedance of D+ and D– traces should match the cable characteristic differential impedance for optimal performance.

Route the high-speed USB signals using a minimum of vias and corners which will reduce signal reflections and impedance changes. When a via must be used, increase the clearance size around it to minimize its capacitance. Each via introduces discontinuities in the signal's transmission line and increases the chance of picking up interference from the other layers of the board. Be careful when designing test points on twisted pair lines; through-hole pins are not recommended.

When it becomes necessary to turn 90°, use two 45° turns or an arc instead of making a single 90° turn. This reduces reflections on the signal traces by minimizing impedance discontinuities.

Do not route USB traces under or near crystals, oscillators, clock signal generators, switching regulators, mounting holes, magnetic devices or IC's that use or duplicate clock signals.

Avoid stubs on the high-speed USB signals because they cause signal reflections. If a stub is unavoidable, then the stub should be less than 200 mm.

Route all high-speed USB signal traces over continuous planes (V_{CC} or GND), with no interruptions.

Avoid crossing over anti-etch, commonly found with plane splits.

A printed circuit board with at least four layers is recommended because of high frequencies associated with the USB; two signal layers separated by a ground and power layer as shown in [Figure 19](#).

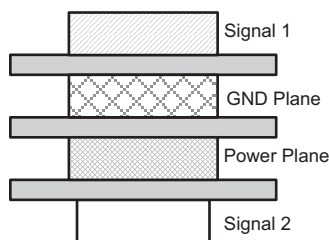


Figure 19. Four-Layer Board Stack-Up

The majority of signal traces should run on a single layer, preferably Signal 1. Immediately next to this layer should be the GND plane, which is solid with no cuts. Avoid running signal traces across a split in the ground or power plane. When running across split planes is unavoidable, sufficient decoupling must be used. Minimizing the number of signal vias reduces EMI by reducing inductance at high frequencies. For more information on layout guidelines, see *High Speed Layout Guidelines* ([SCAA082](#)) and *USB 2.0 Board Design and Layout Guidelines* ([SPRAAR7](#)).

TS3USB221

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11.2 Layout Example

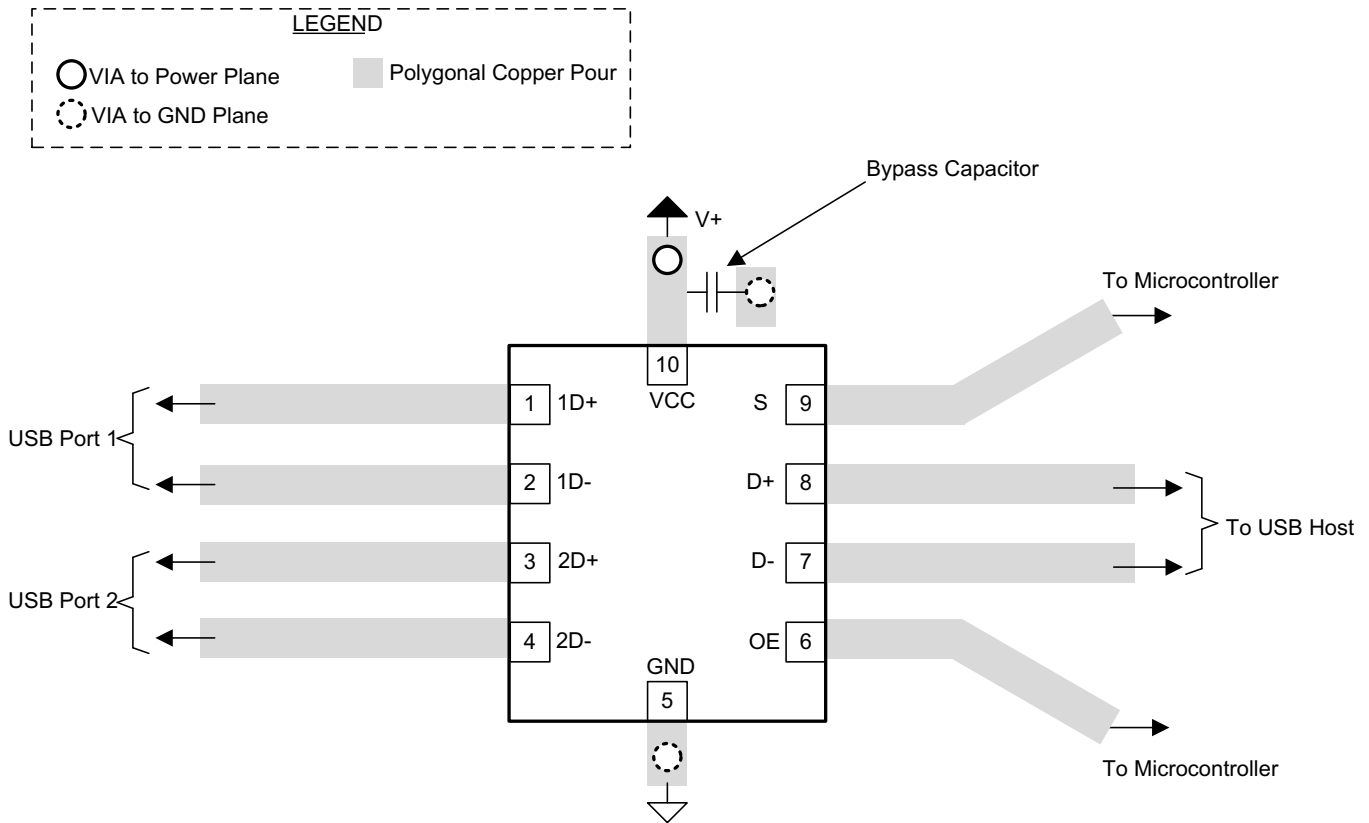


Figure 20. Package Layout Diagram

12 器件和文档支持

12.1 文档支持

12.1.1 相关文档

请参阅如下相关文档：

- 《高速布局指南》，[SCAA082](#)
- 《USB 2.0 电路板设计和布局指南》，[SPRAAR7](#)

12.2 接收文档更新通知

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12.6 术语表

SLYZ022 — TI 术语表。

这份术语表列出并解释术语、缩写和定义。

13 机械、封装和可订购信息

以下页面包含机械、封装和可订购信息。这些信息是指定器件的最新可用数据。数据如有变更，恕不另行通知，且不会对此文档进行修订。如需获取此数据表的浏览器版本，请查阅左侧的导航栏。

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN080104RSER	ACTIVE	UQFN	RSE	10	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(L57, L5O, L5R, L5 V)	Samples
TS3USB221DRCR	ACTIVE	VSON	DRC	10	3000	Green (RoHS & no Sb/Br)	CU NIPDAU CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	ZWG	Samples
TS3USB221DRCRG4	ACTIVE	VSON	DRC	10	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	ZWG	Samples
TS3USB221RSER	ACTIVE	UQFN	RSE	10	3000	Green (RoHS & no Sb/Br)	CU NIPDAU CU NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	(L57, L5O, L5R, L5 V)	Samples
TS3USB221RSERG4	ACTIVE	UQFN	RSE	10	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(L57, L5O, L5R, L5 V)	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TS3USB221DRCR	VSON	DRC	10	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
TS3USB221RSER	UQFN	RSE	10	3000	180.0	9.5	1.7	2.2	0.75	4.0	8.0	Q1
TS3USB221RSER	UQFN	RSE	10	3000	180.0	9.5	1.7	2.3	0.75	4.0	8.0	Q1
TS3USB221RSER	UQFN	RSE	10	3000	180.0	8.4	1.68	2.13	0.76	4.0	8.0	Q1

TAPE AND REEL BOX DIMENSIONS

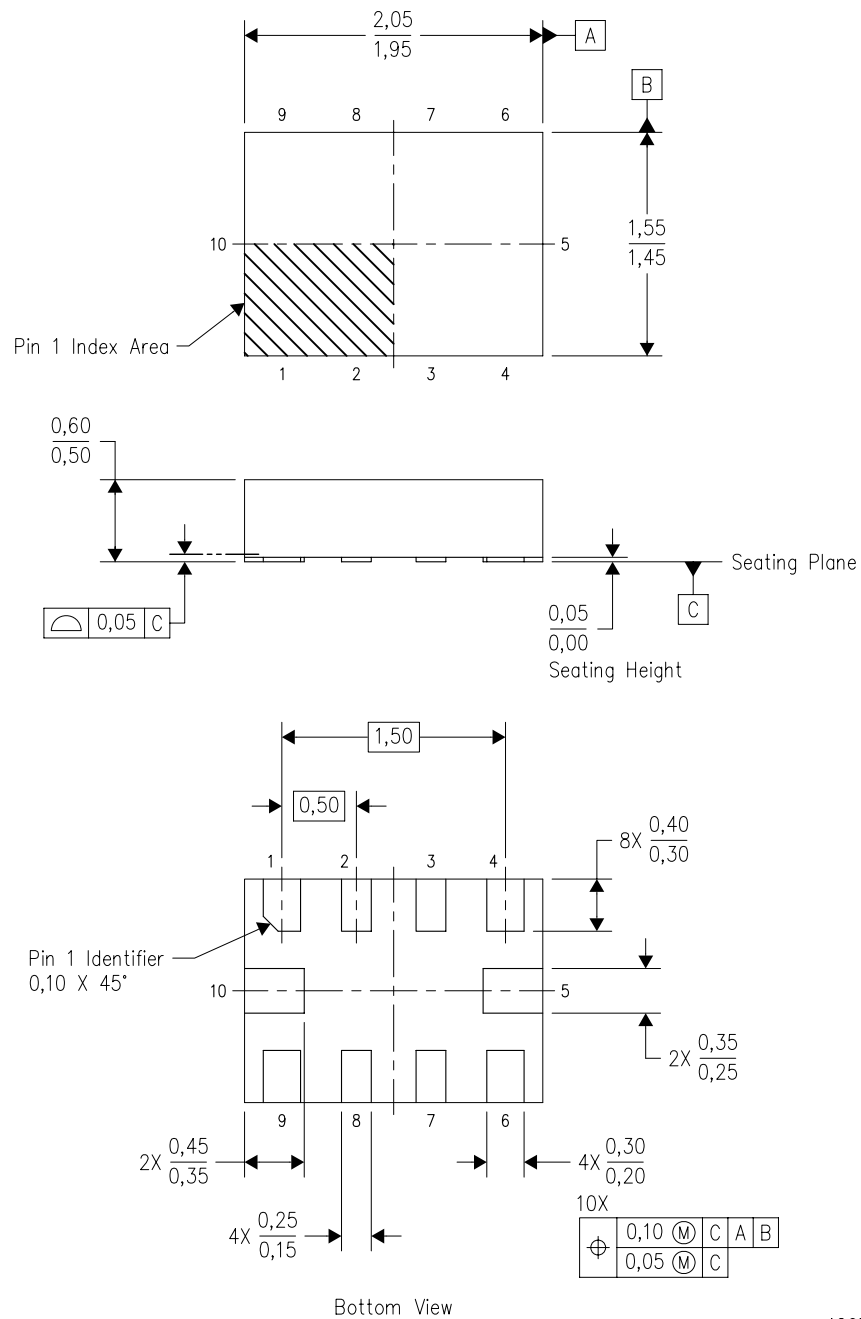


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TS3USB221DRCR	VSON	DRC	10	3000	367.0	367.0	35.0
TS3USB221RSER	UQFN	RSE	10	3000	189.0	185.0	36.0
TS3USB221RSER	UQFN	RSE	10	3000	184.0	184.0	19.0
TS3USB221RSER	UQFN	RSE	10	3000	202.0	201.0	28.0

RSE (R-PUQFN-N10)

PLASTIC QUAD FLATPACK NO-LEAD

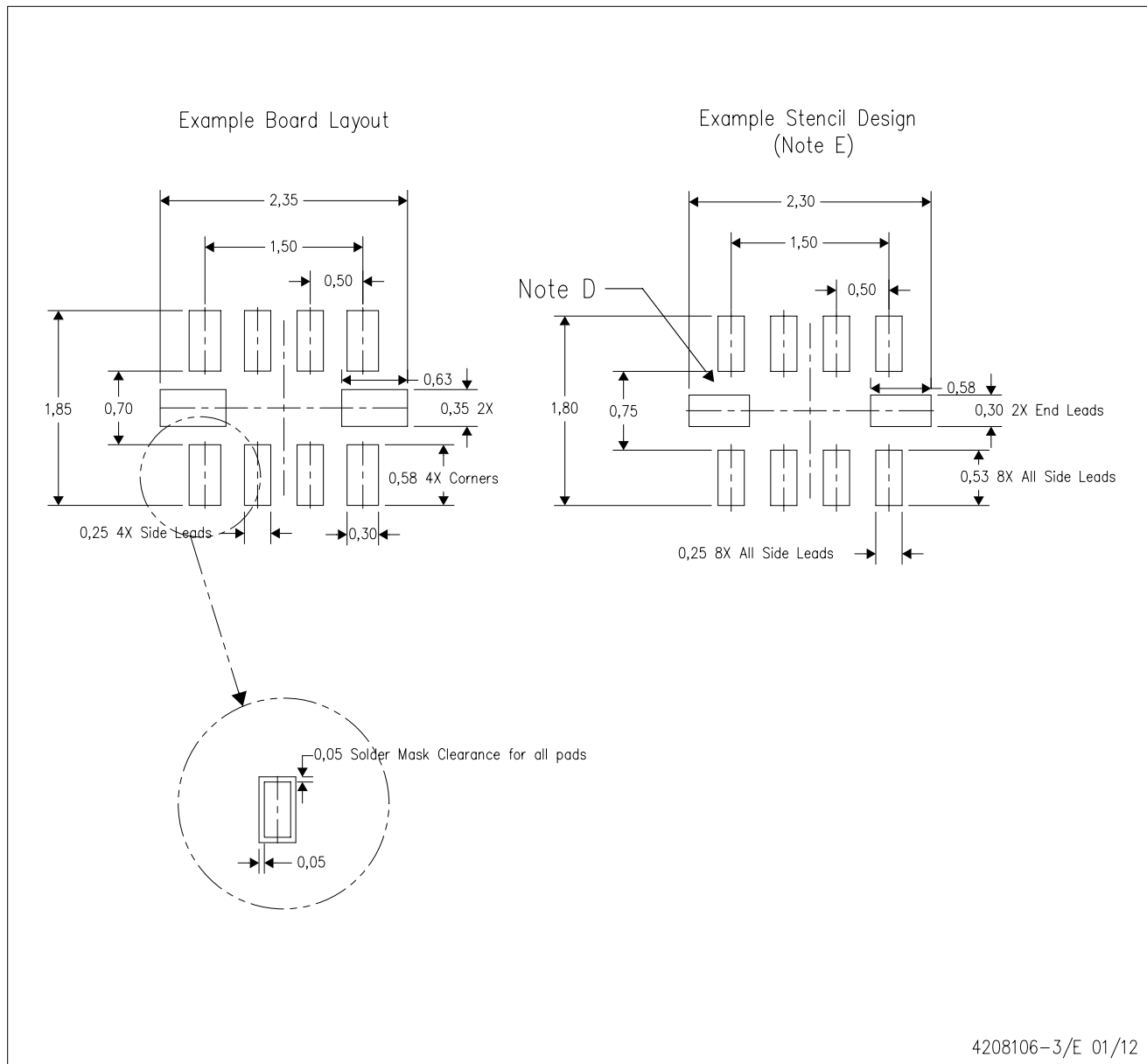


4207268-3/D 01/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) package configuration.
 - D. This package complies to JEDEC MO-288 variation UEFD.

RSE (R-PUQFN-N10)

PLASTIC QUAD FLATPACK NO-LEAD



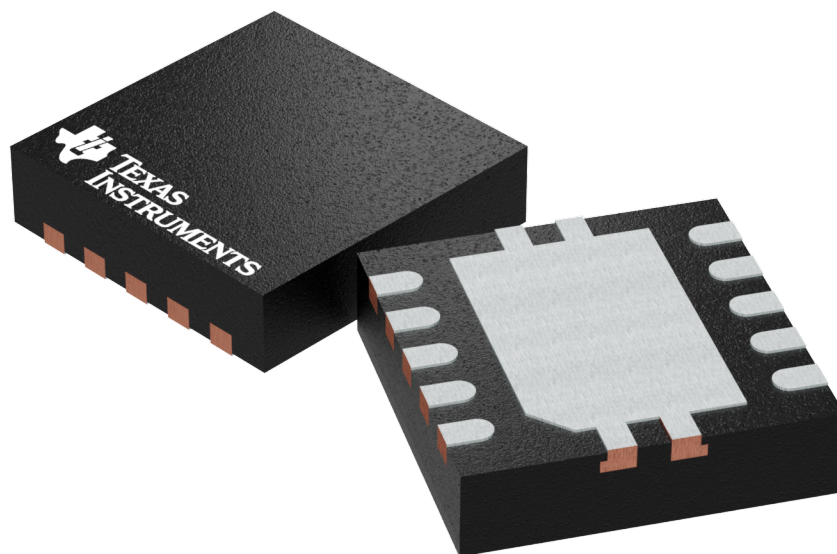
- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.
 - E. Maximum stencil thickness 0,127 mm (5 mils). All linear dimensions are in millimeters.
 - F. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - G. Side aperture dimensions over-print land for acceptable area ratio > 0.66. Customer may reduce side aperture dimensions if stencil manufacturing process allows for sufficient release at smaller opening.

GENERIC PACKAGE VIEW

DRC 10

VSON - 1 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4204102-3/M



VSON - 1 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



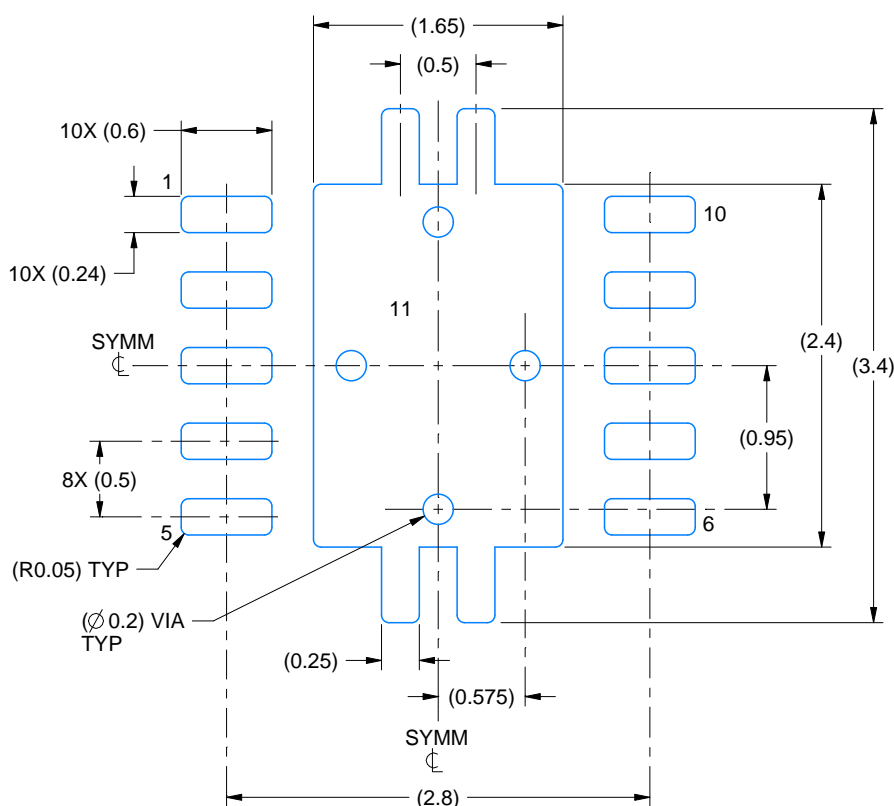
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.

EXAMPLE BOARD LAYOUT

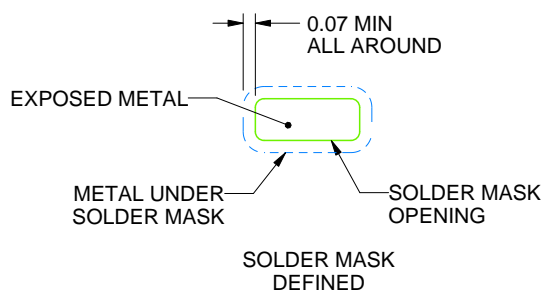
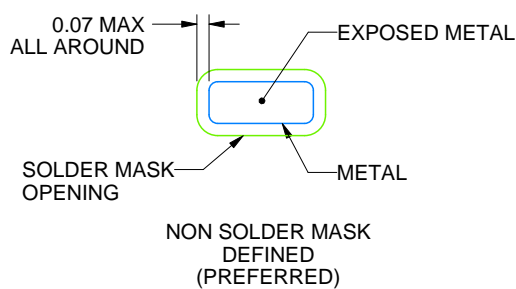
DRC0010J

VSON - 1 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:20X



SOLDER MASK DETAILS

4218878/B 07/2018

NOTES: (continued)

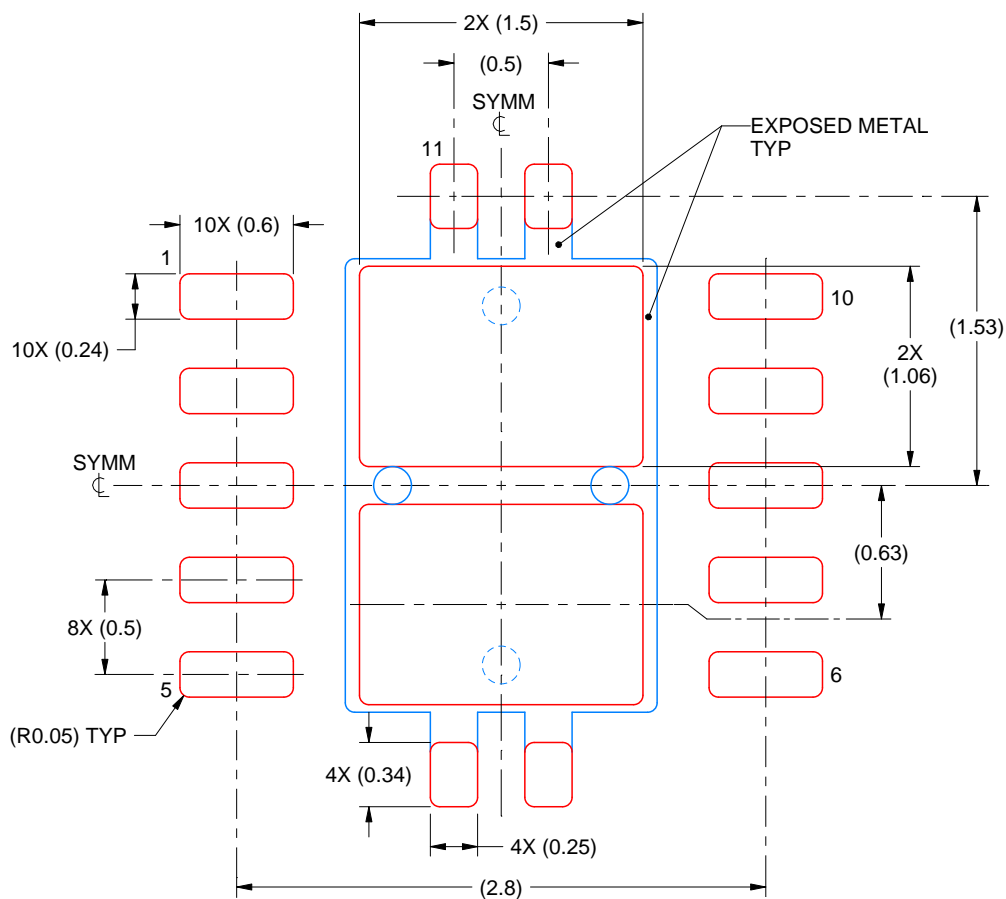
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).

5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

DRC0010J

VSON - 1 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 11:
80% PRINTED SOLDER COVERAGE BY AREA
SCALE:25X

4218878/B 07/2018

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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